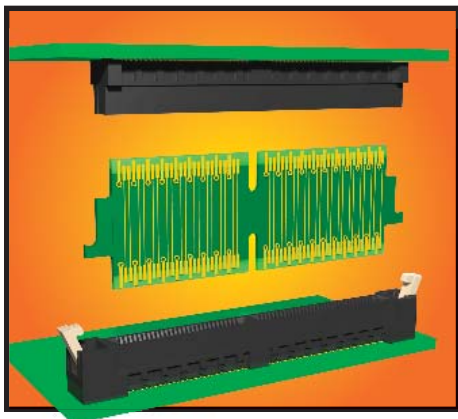


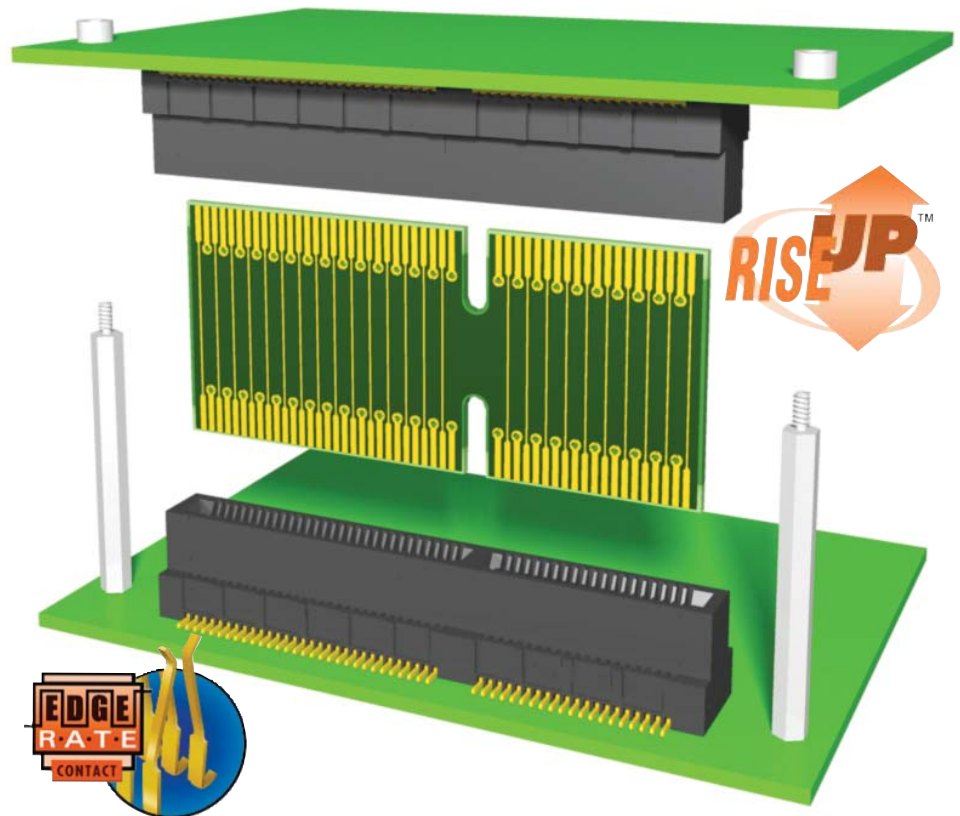
High Speed, Elevated Board Stacking

Samtec's RiseUp® system (RU8 Series) is designed for high speed, elevated board stacking. The two row design saves board real estate and simplifies routing compared to grid design connector systems. The use of a PCB allows odd stack heights to be readily available at a fraction of the cost of custom two piece board stacking systems. Common applications include high speed elevated board stacking to accommodate taller components (such as heat sinks).

The RU8 Series (Samtec's RiseUp® system) consists of two high speed edge card connectors and a riser card that interfaces between the two main boards. The .8mm (.0315") high speed socket (HSEC8 Series) utilizes the Edge Rate™ contact which reduces broadside coupling, providing better impedance control and limiting crosstalk. The riser card (HSC8 Series) has an embedded ground plane that maximizes signal integrity performance and signal pin density. The RU8 Series is rated at 7.5 GHz per pair at a 25mm stack height. For details go to www.samtec.com?RU8.



Board to connector lock (-BL option)



The RU8 system offers standard stack heights of 19mm, 25mm, and 30mm. Stack heights from 17mm up to 60mm are also available as application specific products. The riser card (HSC8 Series) is available in single-ended or differential pair configurations with .062" or .039" card thicknesses. Single-ended systems are available in standard 40, 50, and 60 total signal lines, and the differential pair designs are in 26, 32, and 38 total signal pairs. It is also available in edge mount and right angle options. A board to connector lock (-BL option) for increased retention is also available.

The RU8 Series is used in the telecom, datacom, industrial,

and instrumentation industries and out performs traditional two-piece high speed interconnect systems in elevated applications. The RU8 Series is capable of XAUI, PCI Express, and SATA Data Rates.

Final Inch® is a "reference design" for one of the most difficult design issues on the board - the Breakout Region (BOR) around the connector. Final Inch® Physical Art, Electrical Models, Empirical Signal Integrity Data, and Test and Evaluation Kits are available for the RiseUp® System (RU8 Series). Please visit www.finalinch.com for more information.

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